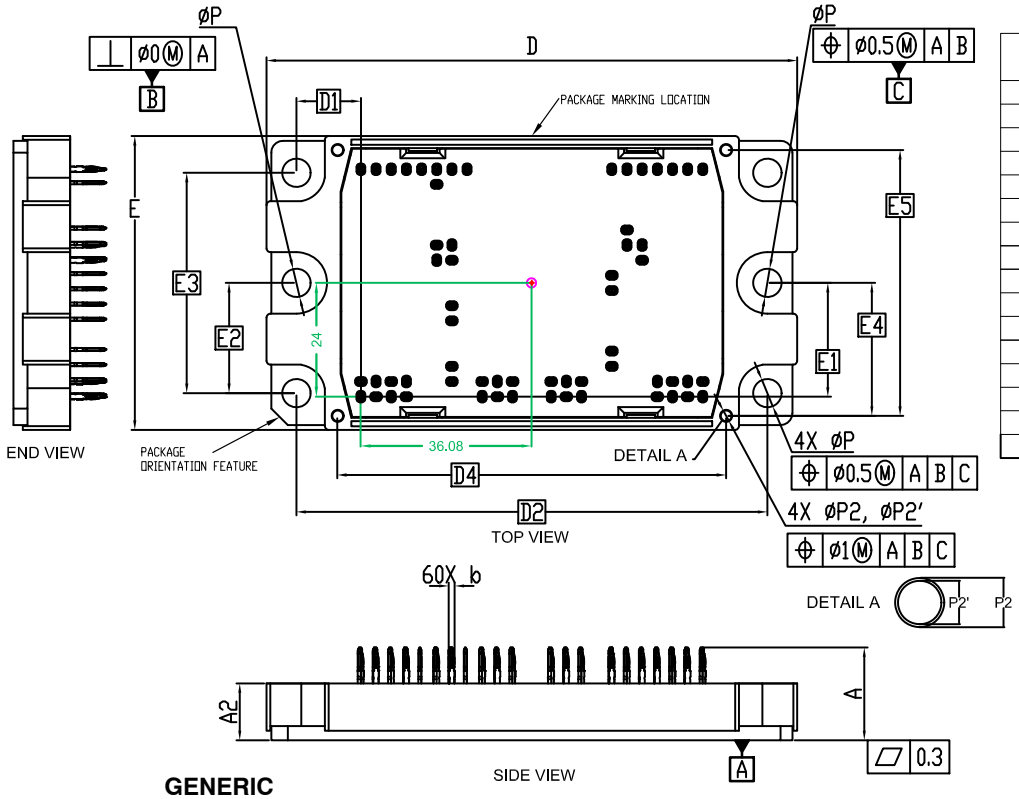


PIM−60 112.00x62.00x12.00
CASE 180DR
ISSUE O

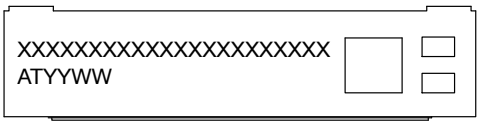
DATE 25 MAR 2026

NOTES:
1. Dimensioning and tolerancing conform to ASME Y14.5 - 2018
2. All dimensions are in millimeters.
3. Pin-grid is 3.2mm.
4. Package marking is located on the side opposite the package orientation feature.
5. The pins are press fit pin (1.2mm)
6. Pin Position tolerance is ±.04mm

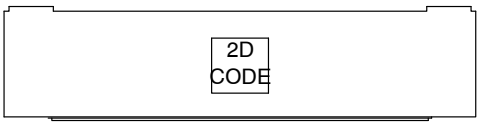


DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	19.20	19.60	20.00
A2	11.70	12.00	12.30
b	1.15	1.20	1.25
D	111.60	112.00	112.40
D1	13.62 BSC		
D2	99.40 BSC		
D4	82.00 BSC		
E	61.60	62.00	62.40
E1	24.00 BSC		
E2	23.25 BSC		
E3	46.50 BSC		
E4	28.05 BSC		
E5	56.10 BSC		
P	5.90	6.00	6.10
P2	2.50	2.60	2.70
P2′	2.30	2.40	2.50

GENERIC MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

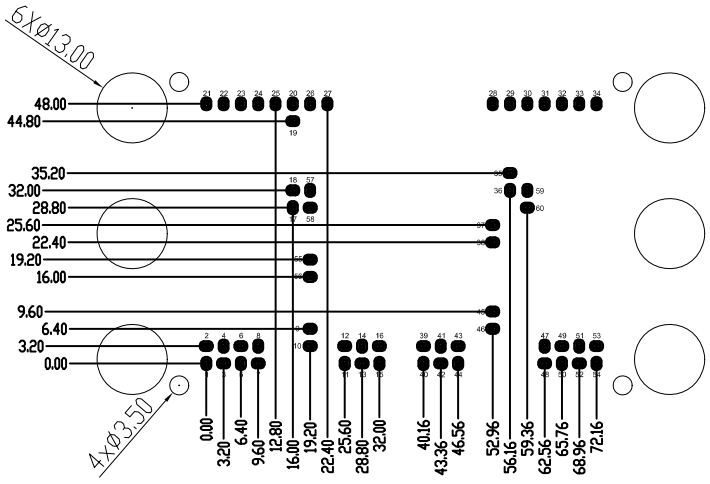
*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪ ”, may or may not be present. Some products may not follow the Generic Marking.

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ISSUE O

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RECOMMENDED
MOUNTING PATTERN

* For additional Information on our Pb−Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTE 2:

Pin table								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0	0	23	6.4	48	45	52.96	9.6
2	0	3.2	24	9.6	48	46	52.96	6.4
3	3.2	0	25	12.8	48	47	62.56	3.2
4	3.2	3.2	26	19.2	48	48	62.56	0
5	6.4	0	27	22.4	48	49	65.76	3.2
6	6.4	3.2	28	52.96	48	50	65.76	0
7	9.6	0	29	56.16	48	51	68.96	3.2
8	9.6	3.2	30	59.36	48	52	68.96	0
9	19.2	6.4	31	62.56	48	53	72.16	3.2
10	19.2	3.2	32	65.76	48	54	72.16	0
11	25.6	0	33	68.96	48	55	19.2	19.2
12	25.6	3.2	34	72.16	48	56	19.2	16
13	28.8	0	35	56.16	35.2	57	19.2	32
14	28.8	3.2	36	56.16	32	58	19.2	28.8
15	32	0	37	52.96	25.6	59	59.36	32
16	32	3.2	38	52.96	22.4	60	59.36	28.8
17	16	28.8	39	40.16	3.2			
18	16	32	40	40.16	0			
19	16	44.8	41	43.36	3.2			
20	16	48	42	43.36	0			
21	0	48	43	46.56	3.2			
22	3.2	48	44	46.56	0			

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